

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	Piotr Strzyzewski
Serial No. 10/	Filing Date: June 23, 2003
Title of Application:	Method And Device For Treating Semiconductor Substrates

Commissioner for Patents
Post Office Box 1450
Alexandria, VA 22313-1450

Preliminary Amendment

Dear Sir:

Please enter this preliminary amendment before examination of this case.

Version with Markings to Show Changes Made to the Claims

In the Claims:

1. (Amended) Method for treating semiconductor substrates, in which the in particular uncoated semiconductor substrates are fed through a loading lock [(1)] to a treatment arrangement, which loading lock [(1)] adjoins a transfer chamber [(2)] from which, in turn, a multiplicity of treatment chambers [(3, 4, 5)] can be loaded with the semiconductor substrates which are to be treated, for which purpose, first of all, the transfer chamber [(2)] and the treatment chamber [(3)] are evacuated, and then a connecting door [(7)] between transfer chamber [(2)] and treatment chamber [(3)] is opened, in which method a low-pressure or atmospheric-pressure process is operated in at least one of the treatment chambers [(4)], and the transfer chamber [(2)] is flooded with an inert gas before the connecting door [(8)] associated with this treatment chamber [(4)] is opened, both the treatment chamber [(4)] and the transfer chamber [(2)], before the connecting door is opened, being purged, in each case at a predefined pressure, with a respective purge gas which remains constant, in such a manner that, when the connecting door is opened, a gas stream flows from the transfer chamber [(2)] into the treatment chamber [(4)] and is maintained during loading of the treatment chamber through the fact that the pressure in the transfer chamber [(2)] is slightly higher than the pressure in the treatment chamber.